

ABSTRACT

The invention is directed to a polishing apparatus including at least: a lower turn table; a motor and a speed reducer for driving the lower turn table; and a box covering at least a portion below a machining surface of the lower turn table, the polishing apparatus pressing a wafer against the lower turn table and polishing the wafer by rotating the lower turn table, the polishing apparatus in which the inside of the box is separated into a plurality of areas by a partition wall, and the motor driving the lower turn table is placed in an area that is different from the area in which the lower turn table is included. This provides a polishing apparatus that can produce a wafer having a stable shape regardless of the time that has elapsed since the operation of the polishing apparatus was started or the presence or absence of a stop.